| ASSOCIATION CONNECTING<br>ELECTRONICS (NDUSTRIES)<br>International and Pan- | C, Bannockt  | ourn, Illinois. A                                     | ll rights reserved utions. | under both This level       | docume<br>parts, th | ent is a declar<br>ne declaration | ation of th<br>n encompa | e substances<br>asses all lowe | within the manufactors within the manufactors are level materials for w | urer listed i<br>which the r    | tem. Note:<br>nanufacture | if the item is an as<br>er has engineering | sembly with lower responsibility. |
|---|--|---|----------------------------|-----------------------------|---------------------|-----------------------------------|--------------------------|--------------------------------|---|---------------------------------|---------------------------|--|-----------------------------------|
|   |  |   |                            | Form Type *<br>Distribute   |                     |                                   |                          |                                | rials and M   | als and Mfg Information         |                           |  |                                   |
| Supplier Information  |  |   |                            |                             |                     |                                   |                          |                                |   |                                 |                           |  |                                   |
| Company name*   | Company unique ID  |   |                            | Unique ID Authority         |                     |                                   |                          |                                | Response Date*  |                                 |                           |  |                                   |
| onsemi  |  |   |                            |                             |                     |                                   |                          |                                | 2025-05   | 2025-05-14                      |                           |  |                                   |
| Contact Name  | Title - Contac   | Title - Contact                                       |                            |                             | Phone - Contact*    |                                   |                          |                                | Email -   | Email - Contact*                |                           |  |                                   |
| Product-Env-Stewards  | Product Enviro Compliance                                  |   |                            | ]                           | NA                  |                                   |                          |                                | Produc  | Product-Env-Stewards@onsemi.com |                           |  |                                   |
| Authorized Representative* Title  |  |   | Title - Representative     |                             |                     | Phone - Representative*           |                          |                                | Email -   | Email - Representative*         |                           |  |                                   |
| Product-Env-Stewards  | Product Enviro Compliance                                  |   |                            | 1                           | NA                  |                                   |                          |                                | Produc  | Product-Env-Stewards@onsemi.com |                           |  |                                   |
| Requester Item Number   | Requester Item Number Mfr Item                             |   | Number Mfr Item Name       |                             |                     | Effective Da                      | te Versi                 | ion                            | Manufacturing Site  |                                 | Weight*                   | UOM  | Unit Type                         |
|   | NCV816<br>G  | NCV8164AML180TC<br>G LDO 300 mA AD<br>High PSRR in DF |                            | D 1V8, Ultra-Low No<br>FNW8 | ise and             | 1 2025-05-14 TH6                  |                          | TH6                            |   | 23.83                           | mg                        | Each                                       |                                   |
| Manufacturing Proccess Informat   | on   |   |                            |                             |                     |                                   |                          |                                |   |                                 |                           |  |                                   |
| Terminal Plating / Grid Array Mat   | Terminal Plating / Grid Array Material Terminal Base Alloy |   | Alloy                      | J-STD-020 MSL Rati          | ing                 | Peak Pr                           | ocess Bod                | y Temperatu                    | re Max Time at Pea  | k Tempera                       | ture Num                  | ber of Reflow Cy                           | eles                              |
| Matte Tin (Sn) - annealed CU Alloy  |  |   | 1                          |                             | 260                 |                                   | С                        | 30                             | secor   | nds 3                           |                           |  |                                   |
| Comments  |  |   |                            |                             |                     |                                   |                          |                                |   |                                 |                           |  |                                   |
| level 1 - maximum time at peak temperatu                                    | e during so  | ldering is 10-3                                       | 0 seconds                  |                             |                     |                                   |                          |                                |   |                                 |                           |  |                                   |
| For more information regarding material of                                  | omposition   | please refer to                                       | page 3                     |                             |                     |                                   |                          |                                |   |                                 |                           |  |                                   |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>v others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the  | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and co<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa   | on above   | Supplier Acceptance   | * Accepted                                      |   |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per  | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester   | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska   | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Iomogeneous Material Weight Unit of |      | Unit of Measure | Level    | Substance                    | CAS              | Exempt | Weight | Unit of Measure |
|-------------------------------------|------|-----------------|----------|------------------------------|------------------|--------|--------|-----------------|
| Die                                 | 0.45 | mg              | Supplier | Silicon (Si)                 | 7440-21-3        |        | 0.45   | mg              |
| Die Attach                          | 0.15 | mg              | Supplier | Silver (Ag)                  | 7440-22-4        |        | 0.1275 | mg              |
|                                     |      |                 | Supplier | Acrylic resins               | Proprietary Data |        | 0.0225 | mg              |
| Lead Frame 9.8                      | 9.89 | mg              | Supplier | Tin (Sn)                     | 7440-31-5        |        | 0.0247 | mg              |
|                                     |      |                 | Supplier | Zinc (Zn)                    | 7440-66-6        |        | 0.0218 | mg              |
|                                     |      |                 | Supplier | Chromium (Cr)                | 7440-47-3        |        | 0.0247 | mg              |
|                                     |      |                 | Supplier | Copper (Cu)                  | 7440-50-8        |        | 9.8188 | mg              |
| ead Frame plating                   | 0.04 | mg              | Supplier | Silver (Ag)                  | 7440-22-4        |        | 0.04   | mg              |
| Mold Compound-Black                 | 12.2 | mg              |          | Epoxy resin                  | proprietary data |        | 0.61   | mg              |
|                                     |      |                 | Supplier | Phenolic Resin               | Proprietary Data |        | 0.2806 | mg              |
|                                     |      |                 | Supplier | Silica Amorphous (SiO2)      | 7631-86-9        |        | 0.61   | mg              |
|                                     |      |                 | Supplier | Carbon Black (C)             | 1333-86-4        |        | 0.0488 | mg              |
|                                     |      |                 | Supplier | Aluminum Hydroxide (Al(OH)3) | 21645-51-2       |        | 0.2806 | mg              |
|                                     |      |                 | Supplier | Fused Silica (SiO2)          | 60676-86-0       |        | 10.37  | mg              |
| lating                              | 0.75 | mg              | Supplier | Tin (Sn)                     | 7440-31-5        |        | 0.75   | mg              |
| Wire Bond - Au                      | 0.35 | mg              | Supplier | Gold (Au)                    | 7440-57-5        |        | 0.35   | mg              |

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).